



Material Content Data Sheet



Sales Product Name		BAS 16-02W H6327		Issued		25. September 2017		
MA#		MA000765564						
Package		PG-SCD80-2-1		Weight*		1.88 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		11	
	noble metal	gold	7440-57-5	0.002	0.11		1073	
	inorganic material	silicon	7440-21-3	0.017	0.92	1.03	9168	10252
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		79	
	non noble metal	titanium	7440-32-6	0.001	0.04		397	
	non noble metal	chromium	7440-47-3	0.002	0.12		1191	
	non noble metal	copper	7440-50-8	0.744	39.54	39.71	395365	397032
wire	non noble metal	copper	7440-50-8	0.002	0.11	0.11	1092	1092
encapsulation	organic material	carbon black	1333-86-4	0.010	0.53		5268	
	plastics	epoxy resin	-	0.169	8.96		89553	
	inorganic material	silicondioxide	60676-86-0	0.813	43.18	52.67	431962	526783
leadfinish	non noble metal	tin	7440-31-5	0.036	1.91	1.91	19127	19127
plating	noble metal	silver	7440-22-4	0.086	4.57	4.57	45714	45714
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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